

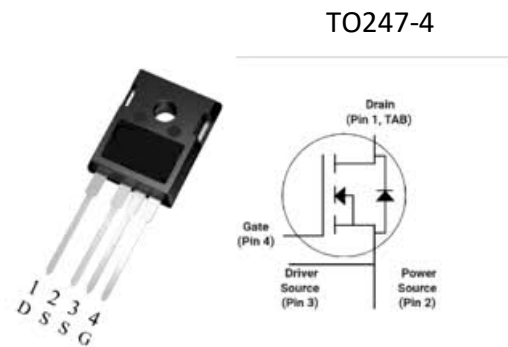
NWK202CJ1-4

1200V Silicon Carbide Mosfet

Parameter	Value	Unit
V_{RRM}	1200	V
$R_{DS(on)}$	20	m Ω
I_D ($T_C = 100^\circ\text{C}$)	96	A

Features

- Optimized package with separate driver source pin
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- RoHS Compliant



Applications

- Electric Vehicle Charging Stations
- Switch Mode Power Supplies
- Motor Drives
- High Voltage DC/DC Converters
- Solar Inverters

Description

The NWK202CJ1-4 is a 1200 V, SiC mosfet based on NovaWave's advanced SiC technology resulting in high performance and long-term reliability. It supports high-temperature operation while showing minimal losses , zero reverse recovery, and low leakage current.

Part Description

Part Number	Package	Marking
NWK202CJ1-4	TO247-4	NWK202CJ1-4

Absolute Maximum Ratings

$T_J = 25^\circ\text{C}$ except as noted. Exceeding the maximum ratings may damage the device.

Parameter	Symbol	Value	Unit	Test conditions
Drain-Source Voltage	$V_{DSS,max}$	1200	V	Static
Continuous Drain Current, limited by $T_{vj(max)}$	I_D	136 96 141 100	A	$T_C = 25^\circ\text{C}$ $V_{GS}=15\text{V}$ $T_C = 100^\circ\text{C}$ $V_{GS}=15\text{V}$ $T_C = 25^\circ\text{C}$ $V_{GS}=18\text{V}$ $T_C = 100^\circ\text{C}$ $V_{GS}=18\text{V}$
Pulse Drain Current, Pulse width t_p limited by $T_{vj(max)}$	$I_{D(pulse)}$	351	A	$T_C = 25^\circ\text{C}$ $V_{GS}=18\text{V}$
Short-circuit withstand time	t_{SC}	3	μs	$V_{DS} \leq 800\text{V}$, $V_{DS,peak} < 1200\text{V}$ $V_{GS,on} = 18\text{V}$, $T_{vj(start)} = 25^\circ\text{C}$
Power Dissipation	P_D	555 278	W	$T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$
Maximum Gate Source Voltage, transient voltage	V_{GSmax}	-10 to +25	V	
Maximum Gate Source Voltage, static voltage	V_{GSmax}	-7 to +23	V	
Recommended turn-on Gate Source Voltage	V_{GSon}	+15 to +18	V	
Recommended turn-off Gate Source Voltage	V_{GSoff}	-5 to -3	V	
Storage Temperature Range	T_{stg}	-55 to +175	$^\circ\text{C}$	
Soldering Temperature	T_L	260	$^\circ\text{C}$	
Virtual junction temperature	T_{vj}	-55 to +175	$^\circ\text{C}$	

Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance from Junction to Case	$R_{TH, J-C}$	--	0.27	--	$^\circ\text{C/W}$

Electrical Characteristics

Parameters	Symbol	Min	Typ	Max	Unit	Condition
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1350			V	$I_D=100\mu A, V_{GS}=0V$
Zero Gate Voltage Drain Current	I_{DSS}		0.1	10	μA	$V_{DS}=1200V, V_{GS}=0V, T_{vj}=25^\circ C$
Gate-Source Leakage Current	I_{GSS}		1	50	nA	$V_{GS}=23V$
Gate Threshold Voltage	$V_{GS(th)}$	1.9	2.6 1.8	3.7	V	$V_{DS}=V_{GS}, I_D=18mA, T_{vj}=25^\circ C$ $V_{DS}=V_{GS}, I_D=18mA, T_{vj}=175^\circ C$
Drain-Source On-State Resistance	$R_{DS(on)}$		20		m Ω	$V_{GS} = 15 V, I_D = 41 A, T_{vj} = 25^\circ C$
			27			$V_{GS} = 15 V, I_D = 41 A, T_{vj} = 150^\circ C$
			30			$V_{GS} = 15 V, I_D = 41 A, T_{vj} = 175^\circ C$
			16			$V_{GS} = 18 V, I_D = 41 A, T_{vj} = 25^\circ C$
			26			$V_{GS} = 18 V, I_D = 41 A, T_{vj} = 150^\circ C$
			28			$V_{GS} = 18 V, I_D = 41 A, T_{vj} = 175^\circ C$
Transconductance	g_{fs}		42 40		S	$V_{DS}=20V, I_{DS}=41A, T_{vj}=25^\circ C$ $V_{DS}=20V, I_{DS}=41A, T_{vj}=175^\circ C$
Input Capacitance	C_{iss}		4509		pF	$V_{DS}=1200V, f=100KHz, V_{GS}=0V$ $V_{AC}=25mV$
Output Capacitance	C_{oss}		185		pF	
Reverse Transfer Capacitance	C_{rss}		11		pF	
C _{oss} Stored Energy	E_{oss}		142		μJ	
Output Charge	Q_{oss}		359		nC	
Internal Gate Resistance	$R_{G(int)}$		2.1		Ω	$f=1MHz, V_{AC}=25mV$
Total Gate Charge	Q_g		180		nC	$V_{DS}=800V, I_D=41A, V_{GS}=-4V/18V$
Gate to Source Charge	Q_{gs}		47		nC	
Gate to Drain Charge	Q_{gd}		40		nC	

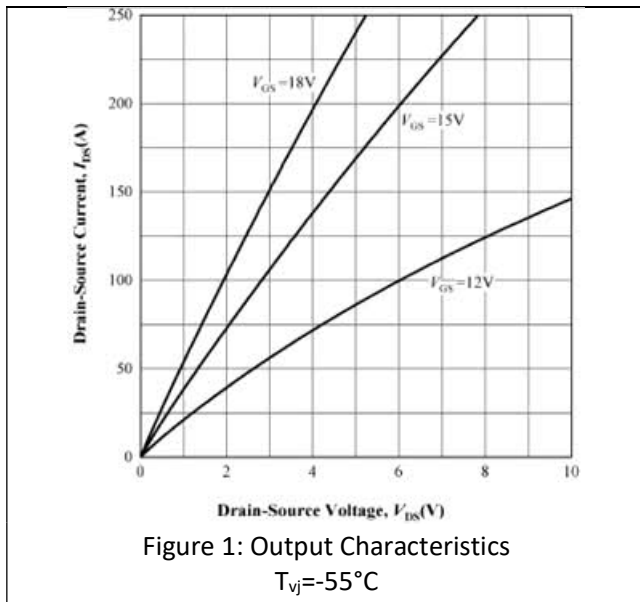
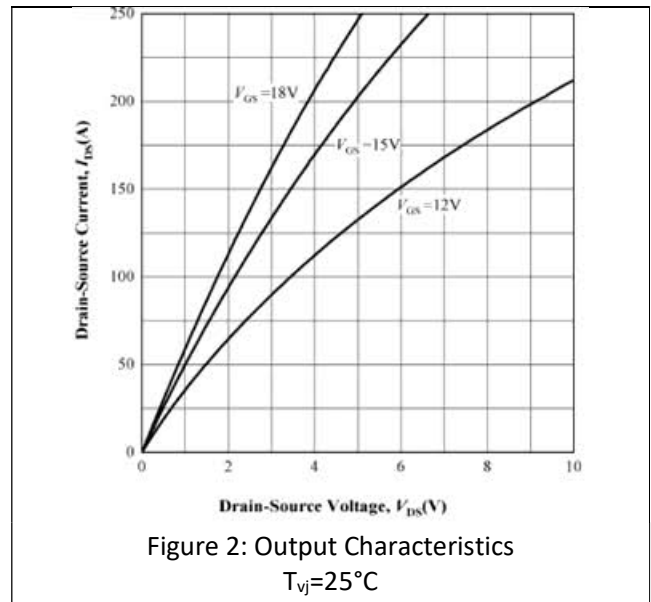
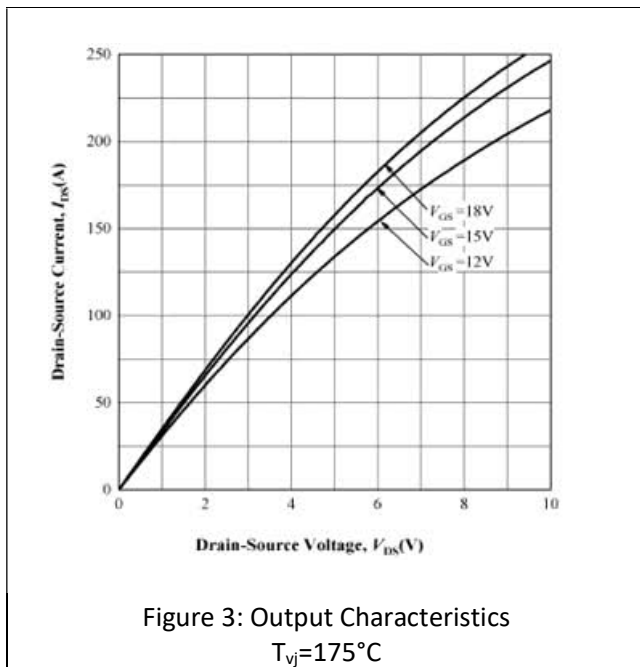
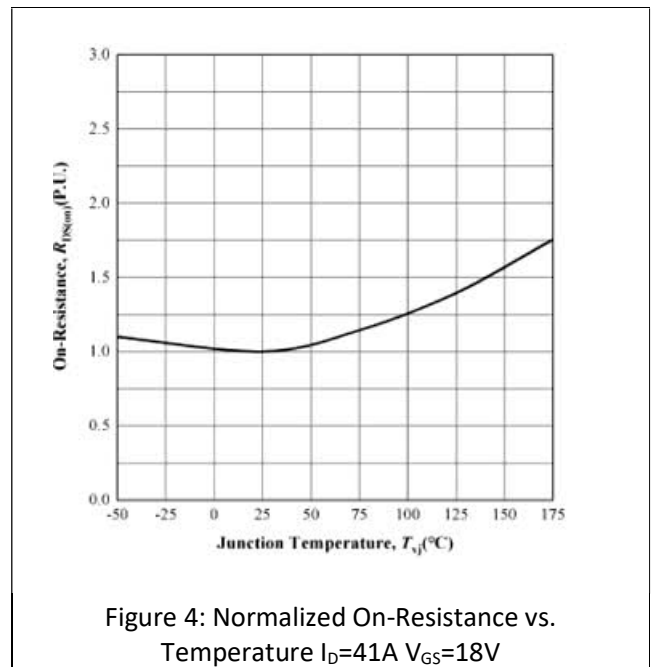
Parameters	Symbol	Min	Typ	Max	Unit	Condition
Turn-On Delay Time	$t_{d(on)}$		32		ns	$V_{DS}=800V$, $I_D=41A$, $V_{GS}=-4V/18V$, $R_{G(on)}=2.5\Omega$, $R_{G(off)}=2.5\Omega$, $L=500\mu H$, $T_{vj}=25^\circ C$ FWD = Body Diode
Rise Time	t_r		23		ns	
Turn-Off Delay Time	$t_{d(off)}$		37		ns	
Fall Time	t_f		11		ns	
Turn-On Energy	E_{on}		578		μJ	
Turn-Off Energy	E_{off}		192		μJ	
Total Switching Energy	E_{Total}		770		μJ	
Turn-On Delay Time	$t_{d(on)}$		29		ns	$V_{DS}=800V$, $I_D=41A$, $V_{GS}=-4V/18V$, $R_{G(on)}=2.5\Omega$, $R_{G(off)}=2.5\Omega$, $L=500\mu H$, $T_{vj}=25^\circ C$ FWD = Body Diode
Rise Time	t_r		22		ns	
Turn-Off Delay Time	$t_{d(off)}$		42		ns	
Fall Time	t_f		12		ns	
Turn-On Energy	E_{on}		890		μJ	
Turn-Off Energy	E_{off}		208		μJ	
Total Switching Energy	E_{Total}		1098		μJ	
Effective output capacitance, energy related	$C_{o(er)}$		197		pF	$V_{GS} = 0 V$, $V_{DS} = 0 \dots 1200 V$
Effective output capacitance, time related	$C_{o(tr)}$		299		pF	$V_{GS} = 0 V$, $V_{DS} = 0 \dots 1200 V$ $I_D = \text{constant}$



Reverse Diode Characteristics

Parameters	Symbol	Min	Typ	Max	Unit	Condition
Diode Forward Voltage	V_{SD}		3.0		V	$V_{GS}=0V, I_S=41A, T_j=25^{\circ}C$
Continuous Diode Forward Current	I_S			141	A	$V_{GS}=-4V, T_c=25^{\circ}C,$
Diode pulse Current	$I_{S(pulse)}$		18		ns	Pulse width t_p , limited by $T_{vj(max)}$

Electrical Performance Graphs



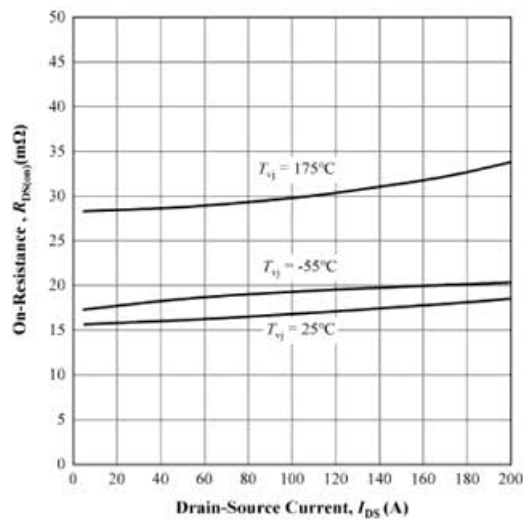


Figure 5: On-Resistance vs. Drain Current for Various Temperature $V_{GS}=18\text{V}$

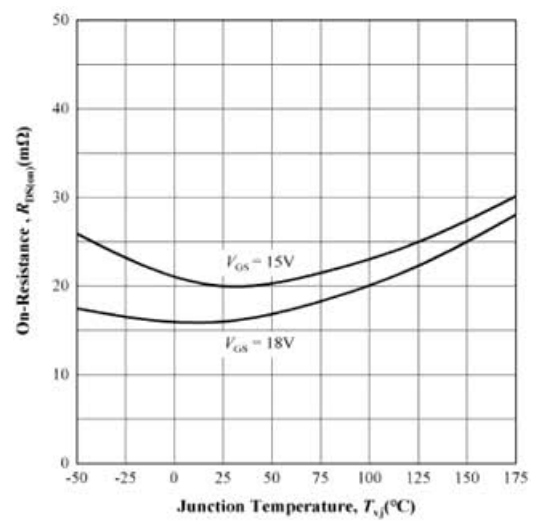


Figure 6: On-Resistance vs. Junction Temperature For Various Gate Voltage $I_D=41\text{A}$

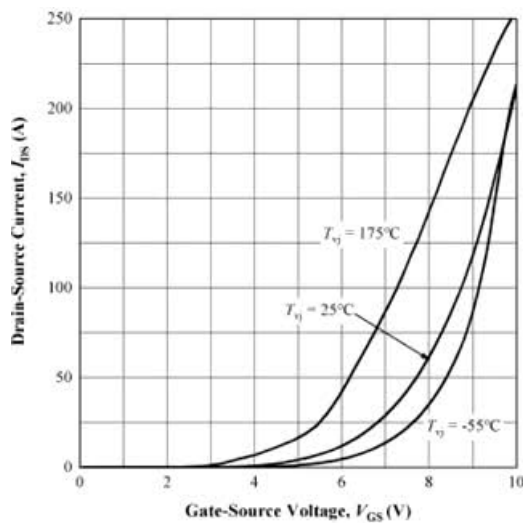


Figure 7: Transfer Characteristic for Various Temperatures $V_{DS}=20\text{V}$

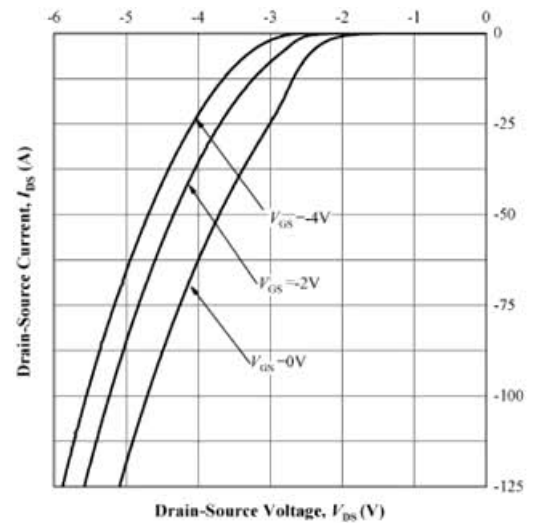


Figure 8: Body Diode Characteristic $T_{vj}=-55^\circ\text{C}$

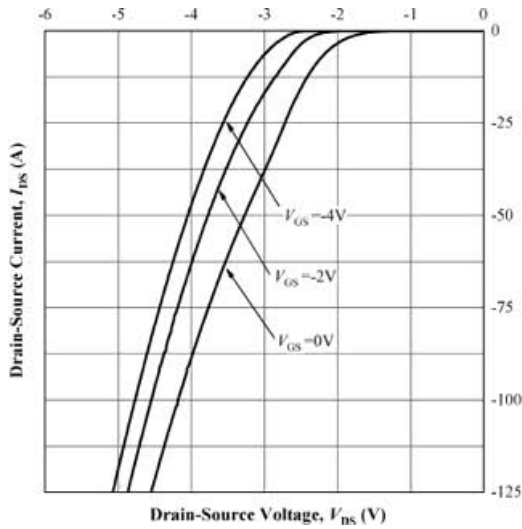


Figure 9: Body Diode Characteristic
 $T_{vj}=25^{\circ}\text{C}$

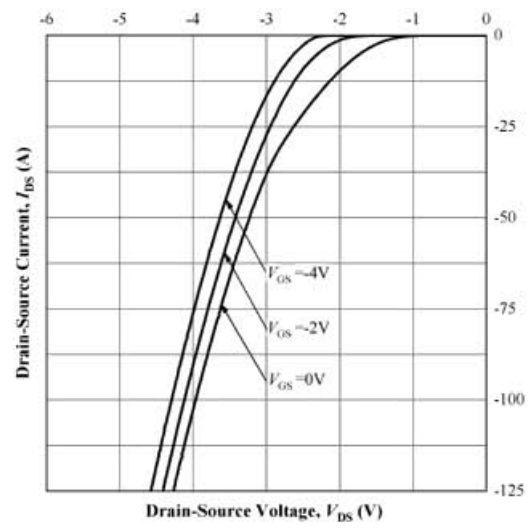


Figure 10: Body Diode Characteristic
 $T_{vj}=175^{\circ}\text{C}$

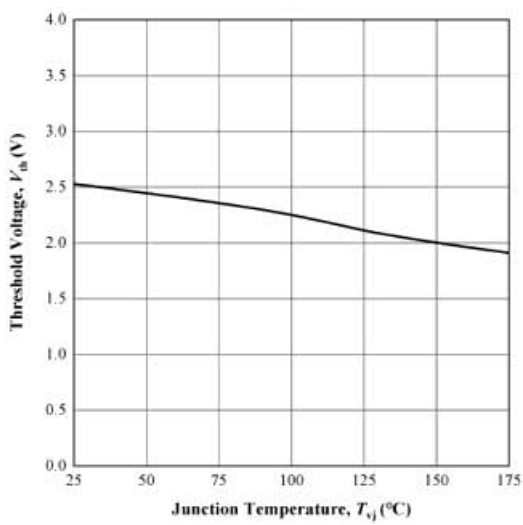


Figure 11. Threshold Voltage vs.
Temperature $V_{GS} = V_{DS}$, $I_D = 18\text{ mA}$

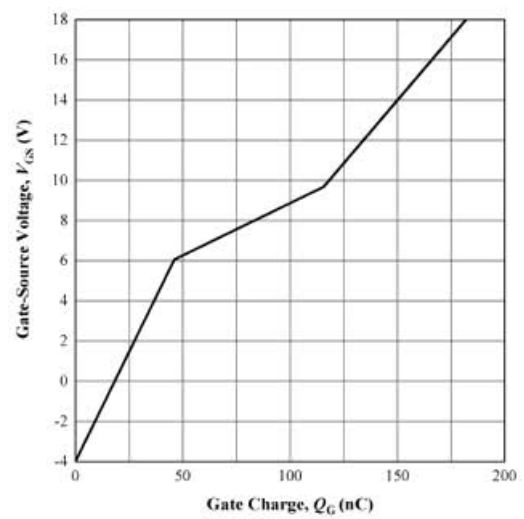


Figure 12. Gate Charge Characteristics
 $V_{DS} = 800\text{ V}$, $T_{vj} = 25^{\circ}\text{C}$

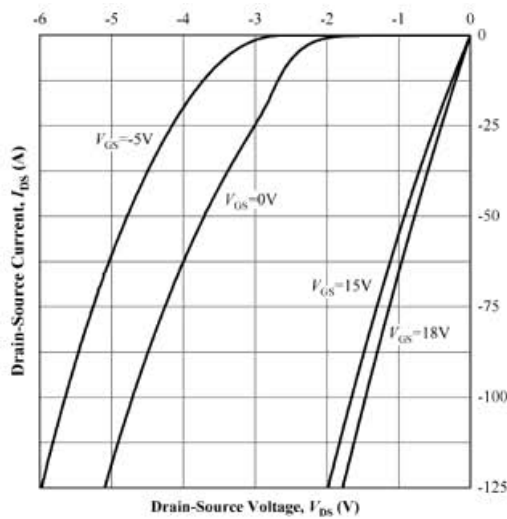


Figure 13. 3rd Quadrant Characteristic
 $T_{vj} = -55^{\circ}\text{C}$

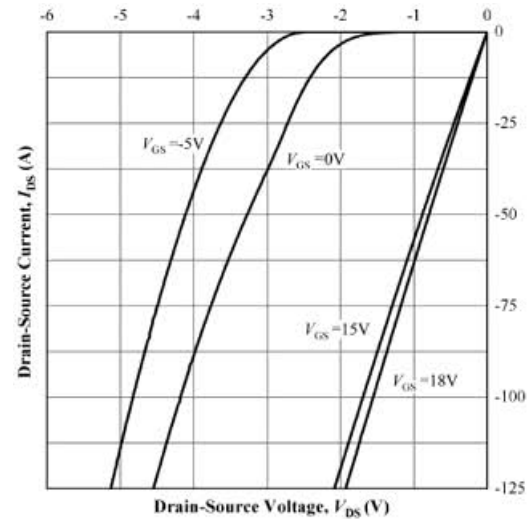


Figure 14. 3rd Quadrant Characteristic
 $T_{vj} = 25^{\circ}\text{C}$

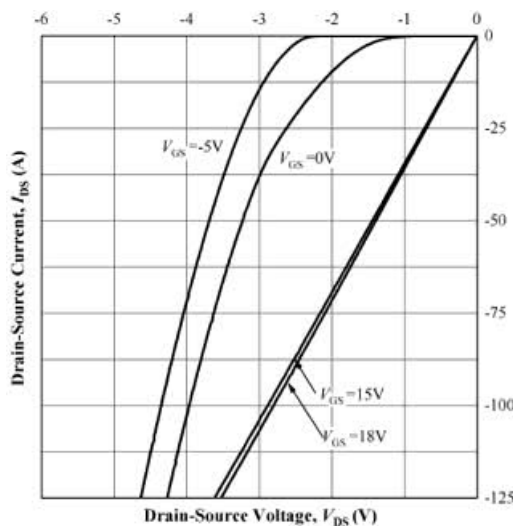


Figure 15. 3rd Quadrant Characteristic
 $T_{vj} = 175^{\circ}\text{C}$

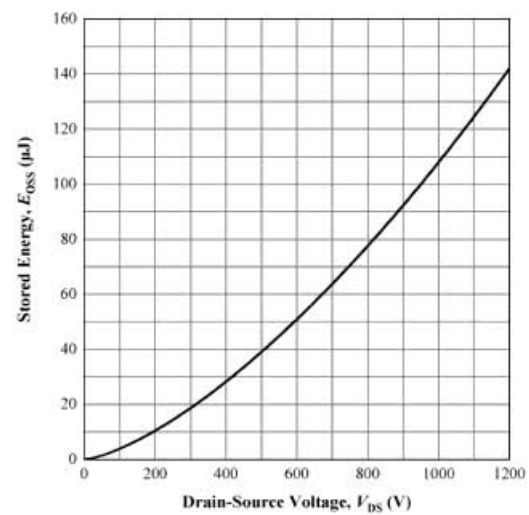


Figure 16. Output Capacitor Stored Energy

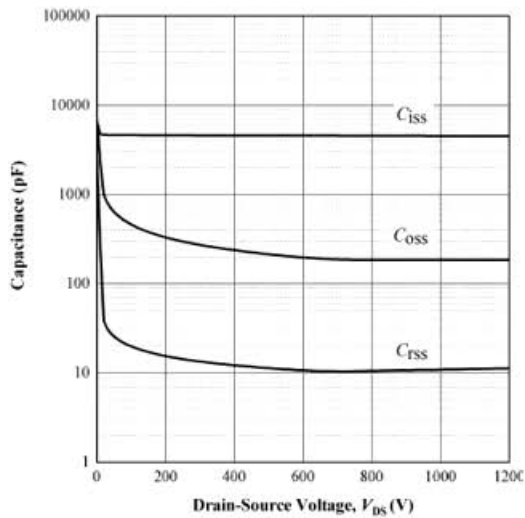


Figure 17: Capacitances vs. Drain-Source Voltage (0 – 1200 V)

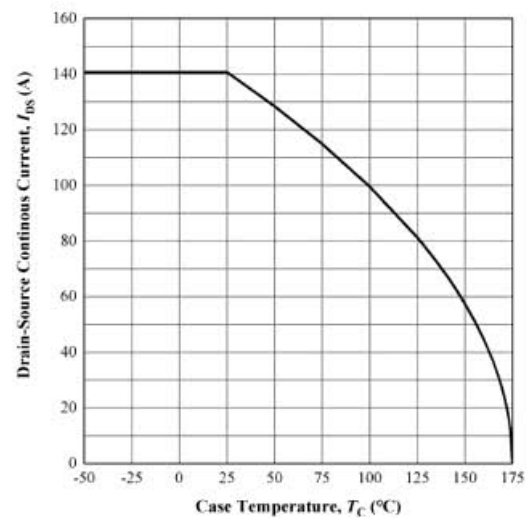


Figure 18: Continuous Drain Current Derating vs. Case Temperature

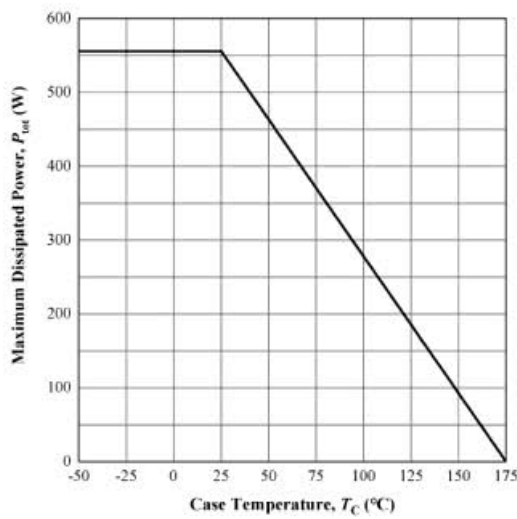


Figure 19: Maximum Power Dissipation Derating vs. Case Temperature

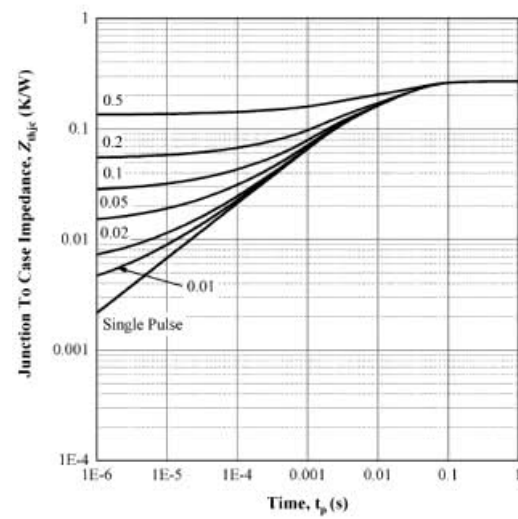


Figure 20: Transient Thermal Impedance

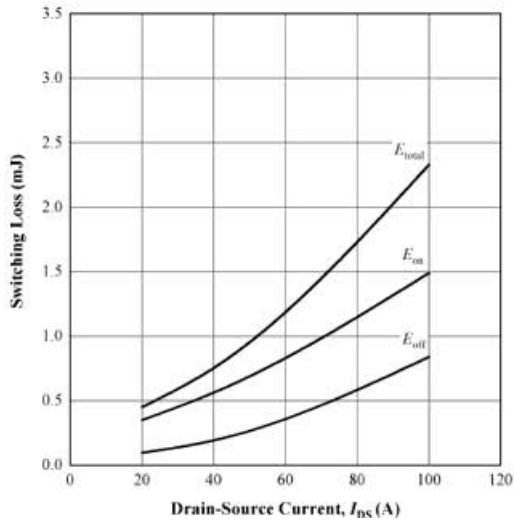


Figure 21: Clamped Inductive Switching Energy vs. Drain Current $T_{vj}=25^{\circ}\text{C}$

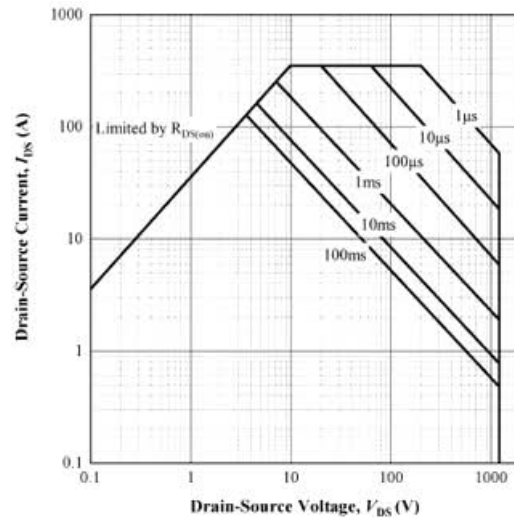


Figure 22: Safe Operating Area

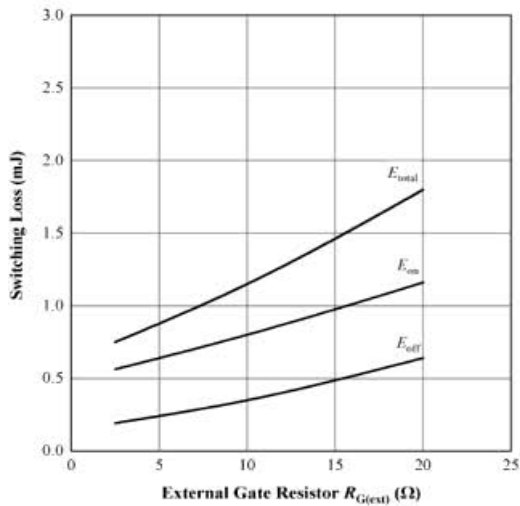


Figure 23: Clamped Inductive Switching Energy vs. $R_{G(ext)}$ $T_{vj}=25^{\circ}\text{C}$

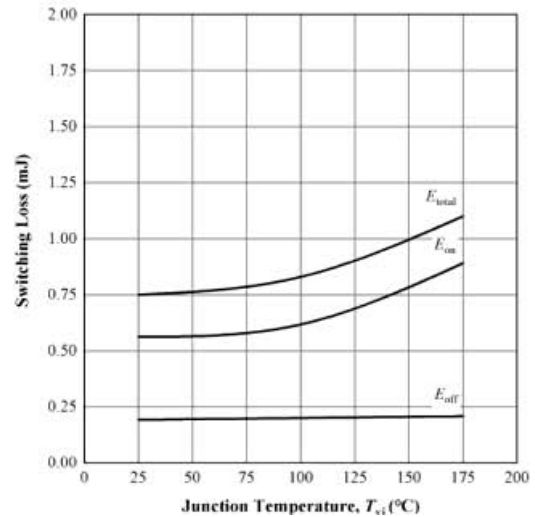


Figure 24: Clamped Inductive Switching Energy vs. Temperature

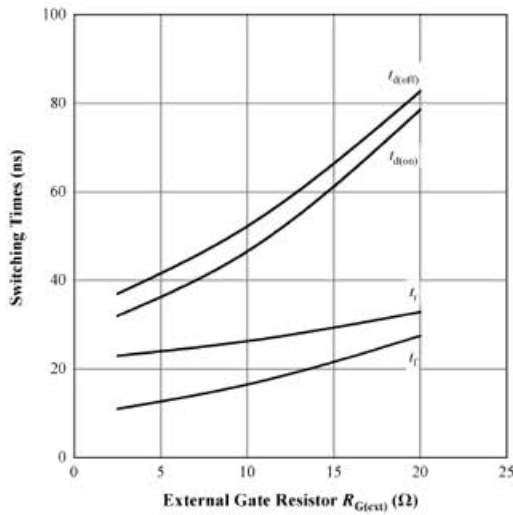


Figure 25: Switching Times vs. $R_{G(ext)}$
 $T_{vj}=25^{\circ}\text{C}$

Testing conditions

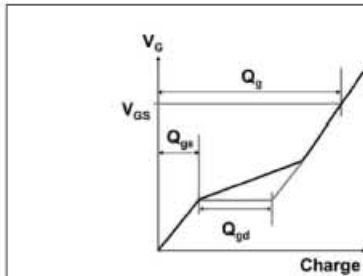


Figure A: Definition of Q_{gd}

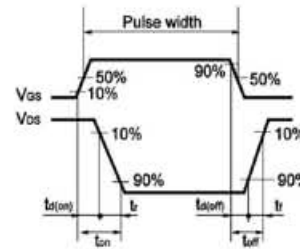


Figure B: Definition of switching times

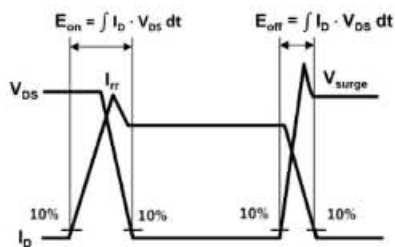


Figure C: Definition of switching losses

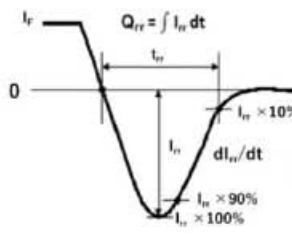
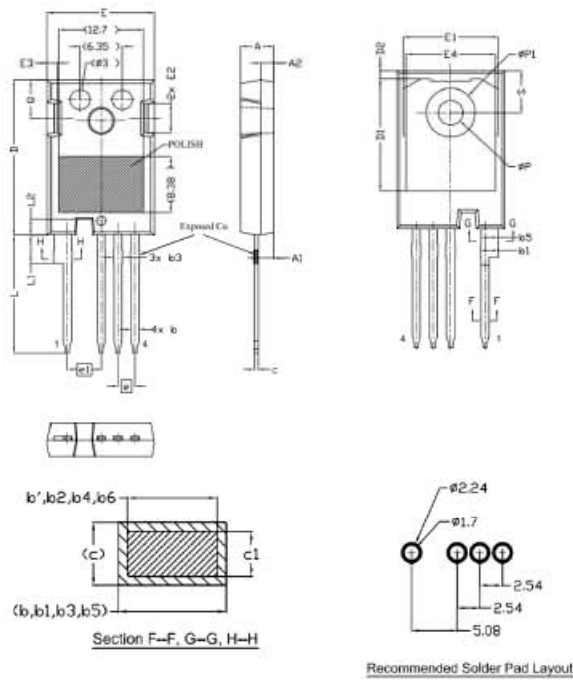


Figure D: Definition of reverse recovery

Package Dimensions

Package: TO-247-4



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.83	5.02	5.21
A1	2.29	2.41	2.54
A2	1.91	2.00	2.16
d	1.07	1.20	1.28
b	1.07	1.20	1.33
b1	2.39	2.57	2.64
b2	2.39	2.57	2.64
b3	1.07	1.30	1.30
b4	1.07	1.30	1.50
b5	2.39	2.53	2.69
b6	2.39	2.53	2.64
c	0.55	0.90	0.88
c1	0.55	0.90	0.55
D	23.20	23.45	23.60
D1	16.25	16.55	17.65
D2	0.95	1.19	1.25
E	15.75	15.94	16.13
E1	13.10	14.02	14.15
E2	3.68	4.40	5.10
E3	1.00	1.45	1.90
E4	12.38	13.26	13.43
e	2.54 BSC		
e1	5.08 BSC		
L	17.31	17.57	17.82
L1	3.97	4.19	4.37
L2	2.35	2.50	2.65
ØP	3.51	3.61	3.85
ØP1	7.18 REF.		
Q	5.49	5.79	6.00
S	6.04	6.17	6.30

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